Silicon N-Channel Power MOS FET Module

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Application

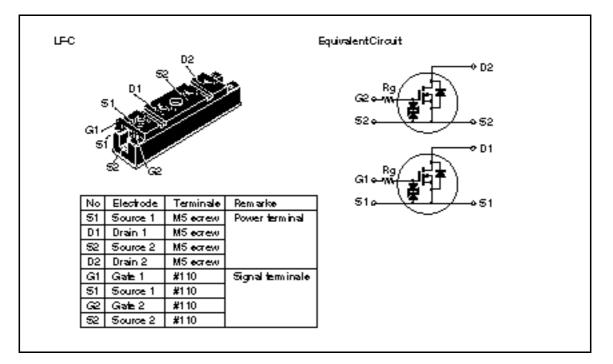
High Speed Power Switching

Features

- Equipped with Power MOS FET
- Low on-resistance
- High speed switching
- Low drive current
- Wide area of safe operation
- Inherent parallel diode between source and drain
- Isolated base from Terminal
- Suitable for motor driver, switching regulator and etc.



Outline



Absolute Maximum Ratings (Ta = 25°C) (Per FET chip)

V _{DSS}	500	V
V _{GSS}	±20	V
I _D	50	А
l _{D(peak)}	100	А
I _{DR}	50	А
DR(peak)	100	А
Pch*1	300	W
Tch	150	°C
Tstg	-45 to +125	°C
Visol*2	2000	V
	I _{D(peak)} I _{DR} I _{DR(peak)} Pch* ¹ Tch Tstg	ID 50 ID(peak) 100 IDR 50 IDR(peak) 100 Pch*1 300 Tch 150 Tstg -45 to +125

Notes: 1. Value at Tc = 25°C

2. Base to terminals AC minute

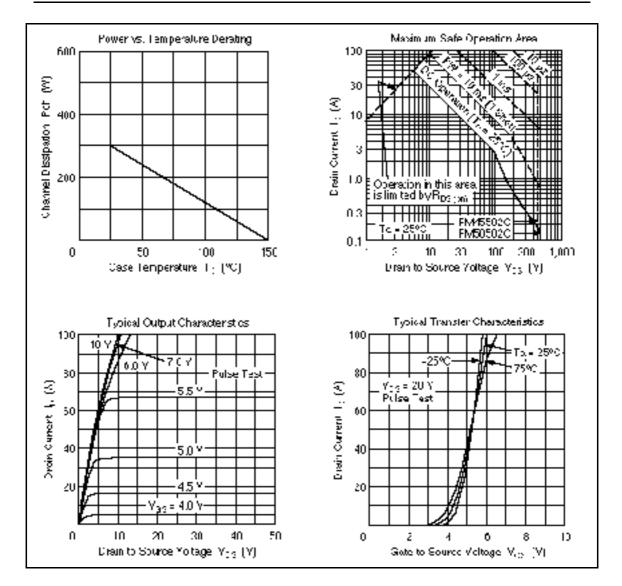
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source breakdown voltage	$V_{(\text{BR})\text{DSS}}$	500	_	_	V	$I_{\rm D} = 10$ mA, $V_{\rm GS} = 0$
Gate to source leak current	I _{GSS}	_	_	±50	μA	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0$
Gate to source breakdown voltage	$V_{\rm (BR)GSS}$	±20	—	—	V	$I_{g} = \pm 100 \ \mu A, \ V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}		_	1	mA	$V_{DS} = 400 \text{ V}, V_{GS} = 0$
Gate to source threshold voltage	$V_{\text{GS(th)}}$	1.5	_	4.0	V	$I_{\rm D} = 1 \text{ mA}, V_{\rm DS} = 10 \text{ V}$
Drain to source saturation voltage	$V_{\text{DS(on)}}$	_	2.25	3.0	V	$I_{\rm D} = 25$ A, $V_{\rm GS} = 10$ V* ¹
Static Drain to source on state resistance	$R_{\text{DS(on)}}$	—	0.09	0.12		$I_{\rm D} = 25$ A, $V_{\rm GS} = 10$ V*1
Forward transfer admittance	y _{fs}	25	40	—	S	$I_{\rm D} = 25$ A, $V_{\rm DS} = 10$ V ^{*1}
Input capacitance	Ciss	_	10250	_	pF	$V_{\rm DS} = 10 \ V, \ V_{\rm GS} = 0,$
Output capacitance	Coss	_	3600	_	pF	f = 1 MHz
Reverse transfer capacitance	Crss	—	400	—	pF	_
Turn-on delay time	t _{d(on)}		150	—	ns	$I_{\rm D} = 25$ A, $V_{\rm GS} = 10$ V,
Rise time	t,	_	700	_	ns	
Turn-off delay time	$t_{d(off)}$	—	800	—	ns	_
Fall time	t _f	_	600	_	ns	_
Body to drain diode forward voltage	V_{DF}	—	1.2	—	V	$I_{F} = 25 \text{ A}, V_{GS} = 0$
Body to drain diode reverse recovery time	t _{rr}	_	200	_	ns	$I_{F} = 25 \text{ A}, V_{GS} = 0,$ diF/dt = 100 A/µs

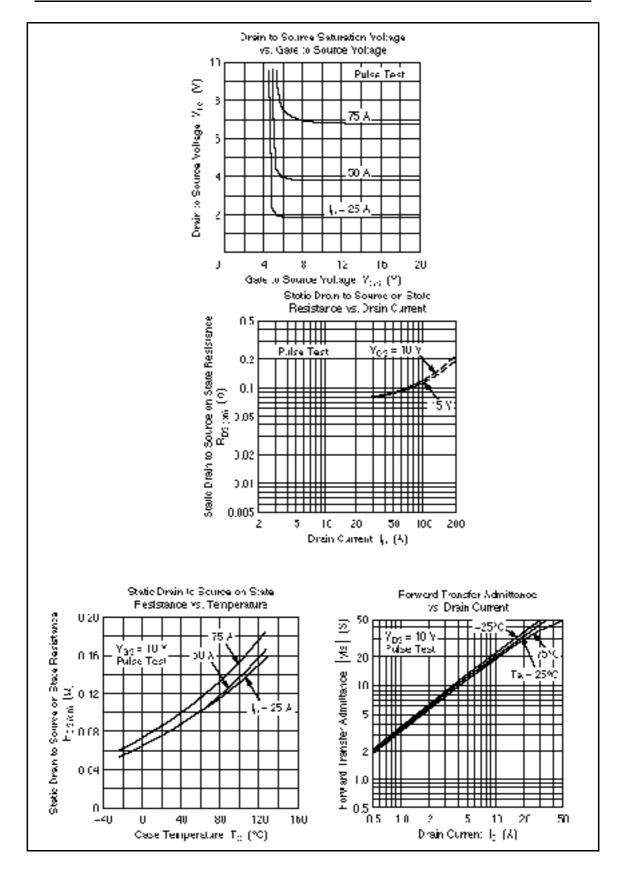
Electrical Characteristics (Ta = 25°C) (Per FET chip)

Note: 1. Pulse Test

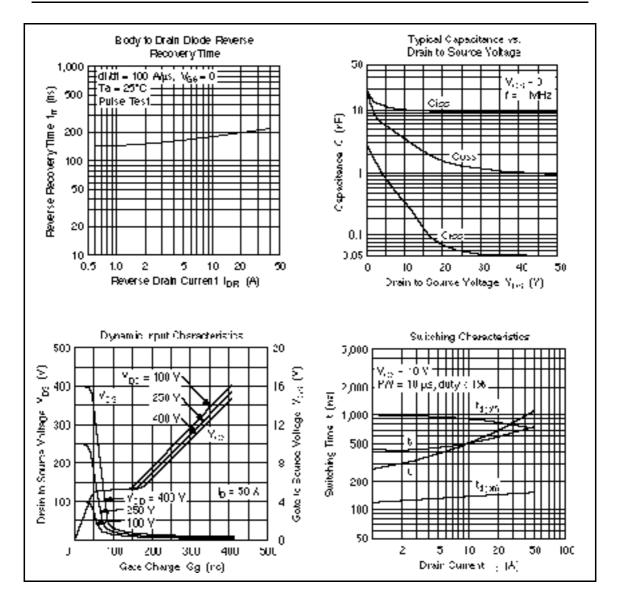
Mechanical Characteristics

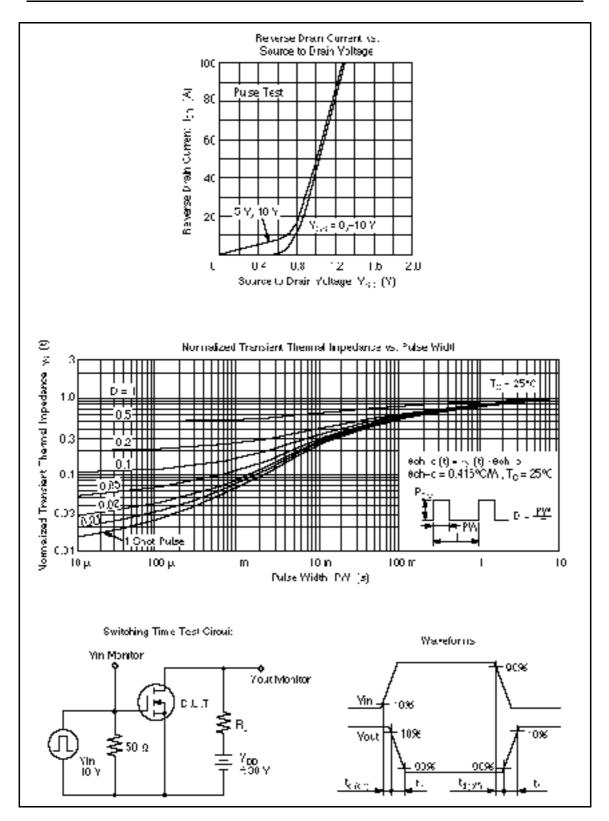
Symbol	Condition	Rating	Unit
_	Mounting into main-terminal with M5 screw	15 to 20	kg∙cm
_	Mounting into heat sink with M6 screw	20 to 30	kg∙cm
_	Typical value	300	g
•	Symbol 	 Mounting into main-terminal with M5 screw Mounting into heat sink with M6 screw 	— Mounting into main-terminal with M5 screw 15 to 20 — Mounting into heat sink with M6 screw 20 to 30





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